

- Functionally Equivalent to AMD's AM29823 and AM29824
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Outputs Have Undershoot-Protection Circuitry
- Power-Up High-Impedance State
- Buffered Control Inputs to Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

description

These 9-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers, parity bus interfacing, and working registers.

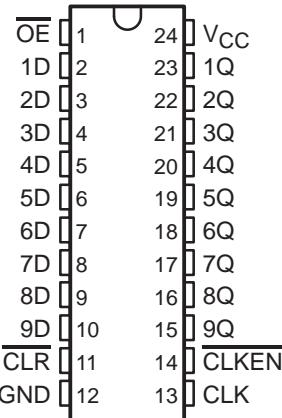
With the clock-enable (CLKEN) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock (CLK) input. Taking CLKEN high disables the clock buffer, latching the outputs. The SN54AS823A and SN74AS823A have noninverting data (D) inputs and the SN74AS824A has inverting (\bar{D}) inputs. Taking the clear (CLR) input low causes the nine Q outputs to go low independently of the clock.

A buffered output-enable (\bar{OE}) input can be used to place the nine outputs in either a normal logic state (high or low logic level) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

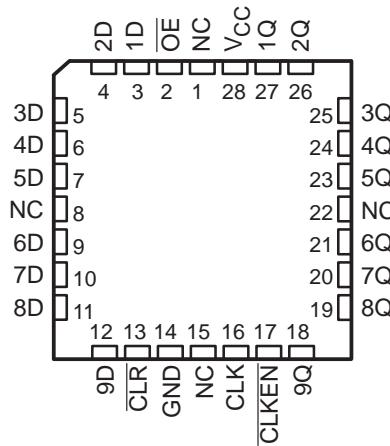
\bar{OE} does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54AS823A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74AS823A and SN74AS824A are characterized for operation from 0°C to 70°C .

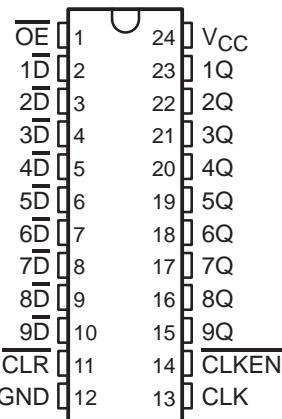
SN54AS823A . . . JT PACKAGE
SN74AS823A . . . DW OR NT PACKAGE
(TOP VIEW)



SN54AS823A . . . FK PACKAGE
(TOP VIEW)



SN74AS824A . . . DW OR NT PACKAGE
(TOP VIEW)



NC – No internal connection

**SN54AS823A, SN74AS823A, SN74AS824A
9-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS**

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Function Tables

**SN54AS823A, SN74AS823A
(each flip-flop)**

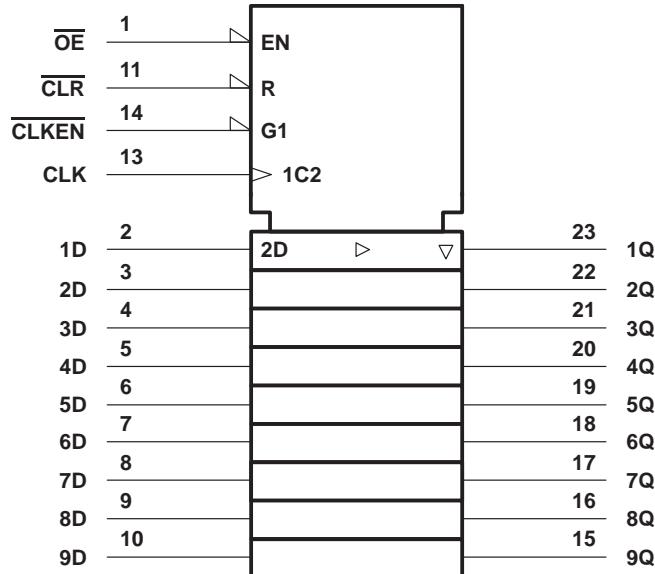
INPUTS					OUTPUT Q
\overline{OE}	\overline{CLR}	\overline{CLKEN}	CLK	D	
L	L	X	X	X	L
L	H	L	\uparrow	H	H
L	H	L	\uparrow	L	L
L	H	H	X	X	Q_0
H	X	X	X	X	Z

**SN74AS824A
(each flip-flop)**

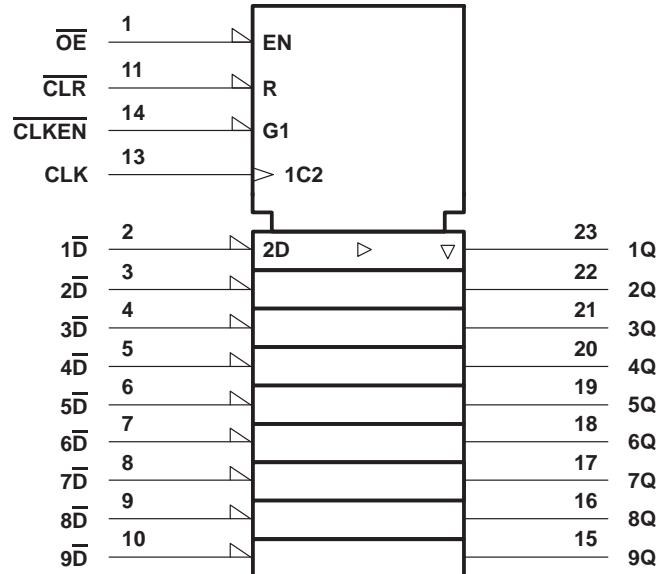
INPUTS					OUTPUT Q
\overline{OE}	\overline{CLR}	\overline{CLKEN}	CLK	\overline{D}	
L	L	X	X	X	L
L	H	L	\uparrow	H	L
L	H	L	\uparrow	L	H
L	H	H	X	X	Q_0
H	X	X	X	X	Z

logic symbols[†]

SN54AS823A, SN74AS823A

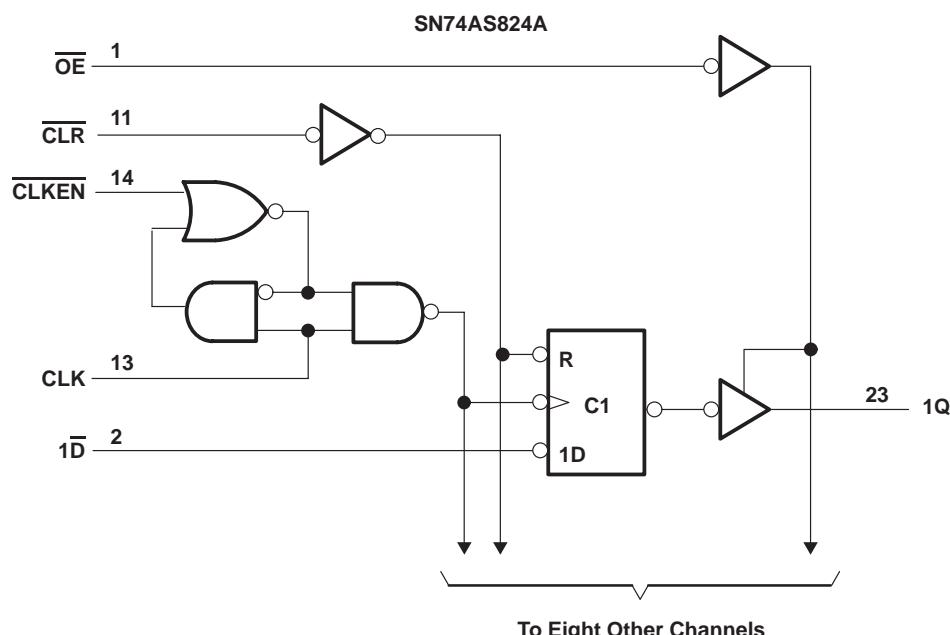
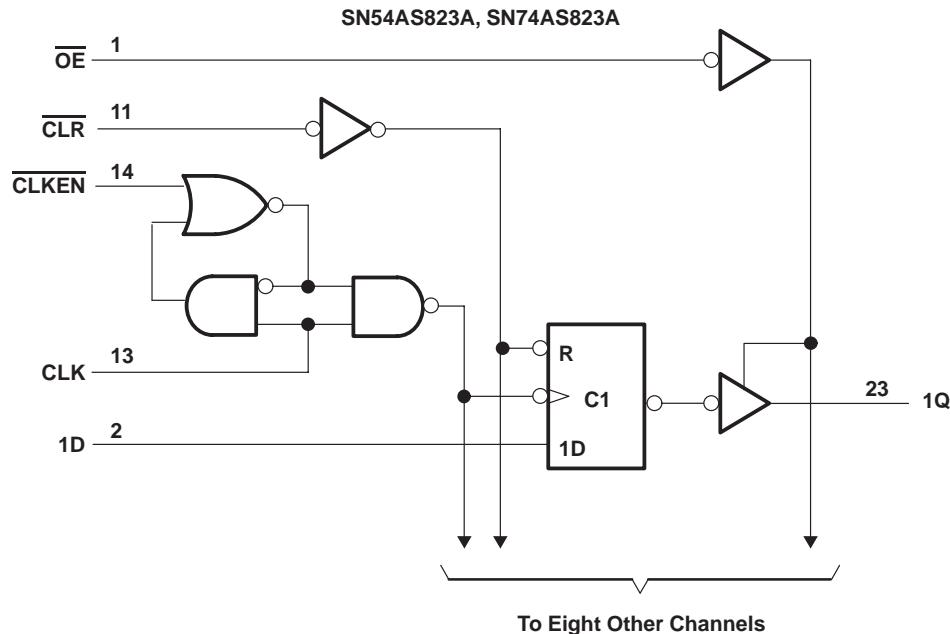


SN74AS824A



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DW, JT, and NT packages.

logic diagrams (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.

SN54AS823A, SN74AS823A, SN74AS824A 9-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS823A			SN74AS823A SN74AS824A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{OH}	High-level output current			-24			-24	mA
I _{OL}	Low-level output current			32			48	mA
t _w *	Pulse duration	CLR low	7.5		6.5			ns
		CLK high or low	9.5		8			
t _{su} *	Setup time before CLK↑	CLR high	8		8			ns
		Data	7		6			
		CLKEN high or low	8.5		7.5			
t _h *	Hold time after CLK↑	CLKEN low	0		0			ns
T _A	Operating free-air temperature	-55	125		0	70		°C

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

**SN54AS823A, SN74AS823A, SN74AS824A
9-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS**

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS823A			SN74AS823A SN74AS824A			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = -2 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -15 \text{ mA}$	2.4	3.2	2.4	3.2		
		$I_{OH} = -24 \text{ mA}$	2		2			
V_{OL}	$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 32 \text{ mA}$	0.3	0.5				V
		$I_{OL} = 48 \text{ mA}$				0.35	0.5	
I_{OZH}	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.7 \text{ V}$			50			50	μA
I_{OZL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$			-50			-50	μA
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20			20	μA
I_{IL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$			-0.5			-0.5	mA
I_O^{\ddagger}	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	-30	-112	-30	-112			mA
I_{CC}	SN54AS823A, SN74AS823A	$V_{CC} = 5.5 \text{ V}$	Outputs high	49	80	49	80	mA
			Outputs low	61	100	61	100	
			Outputs disabled	64	103	64	103	
	SN74AS824A	$V_{CC} = 5.5 \text{ V}$	Outputs high	49	80	49	80	
			Outputs low	61	100	61	100	
			Outputs disabled	64	103	64	103	

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

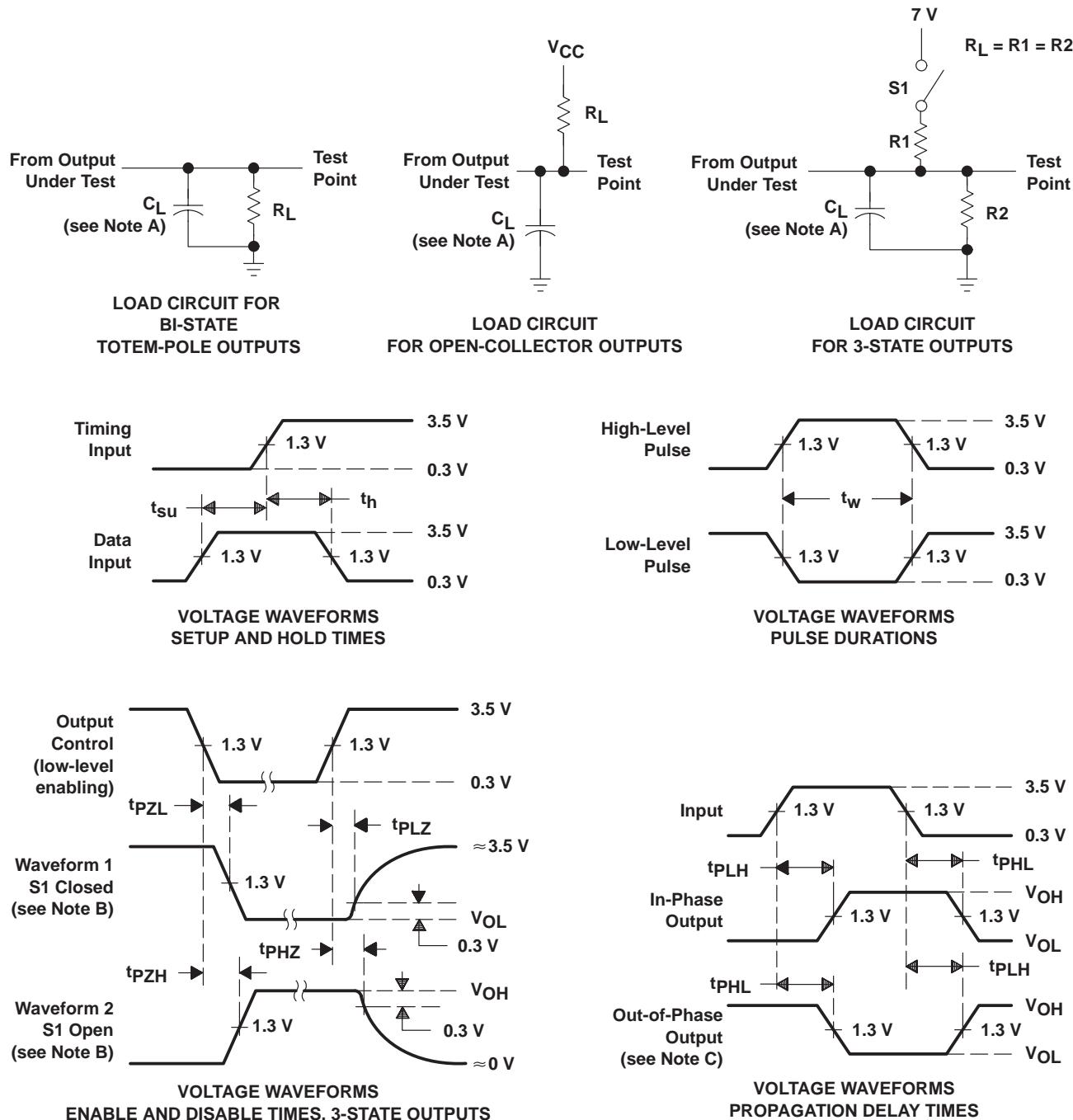
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R1 = 500 \Omega$, $R2 = 500 \Omega$, $T_A = \text{MIN to MAX}^{\$}$				UNIT	
			SN54AS823A		SN74AS823A SN74AS824A			
			MIN	MAX	MIN	MAX		
t_{PLH}	CLK	Any Q	3.5	9	3.5	7.5	ns	
t_{PHL}			3.5	14	3.5	13		
t_{PHL}	$\overline{\text{CLR}}$	Any Q	3.5	16.5	3.5	15.5	ns	
t_{PZH}	$\overline{\text{OE}}$	Any Q	4	12	4	11	ns	
t_{PZL}			4	13	4	12		
t_{PHZ}	$\overline{\text{OE}}$	Any Q	1	10	1	8	ns	
t_{PLZ}			1	10	1.5	8		

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

**SN54AS823A, SN74AS823A, SN74AS824A
9-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS**

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**PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES**



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1 \text{ MHz}$, $t_r = t_f = 2 \text{ ns}$, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8952501LA	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8952501LA SNJ54AS823AJT
SNJ54AS823AJT	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8952501LA SNJ54AS823AJT
SNJ54AS823AJT.A	Active	Production	CDIP (JT) 24	15 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8952501LA SNJ54AS823AJT

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

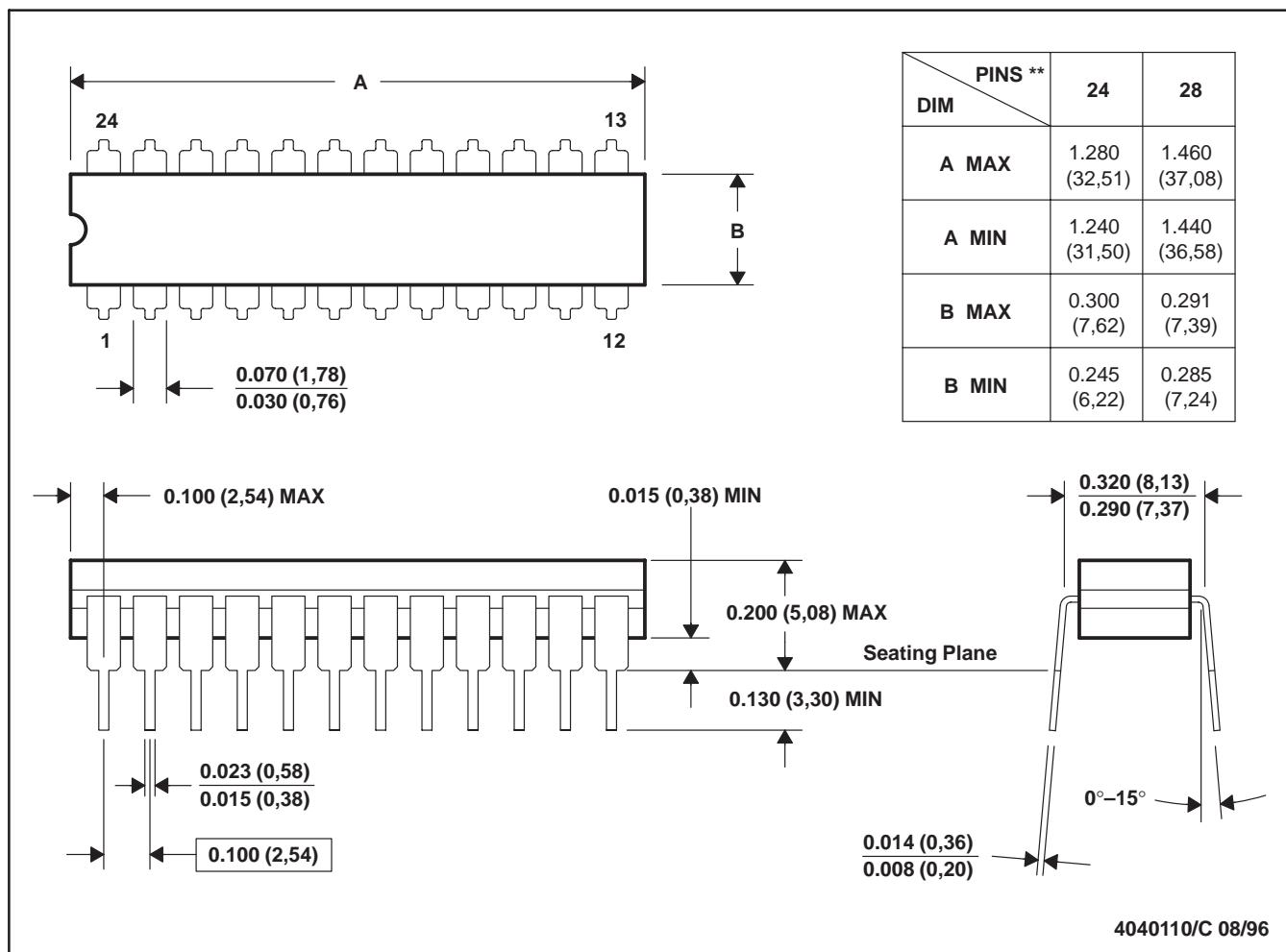
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JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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